

ABSTRACT OF THE DISCLOSURE

A unit for supplying solder balls or the like is configured to have a primary hopper for storing a number of solder balls or the like, a ball tray for storing solder balls
5 or the like, and a ball supply path connecting the primary hopper and the ball tray. A secondary hopper connected to the primary hopper through the ball supply path is provided near the ball tray. A vibration member is added to the secondary hopper, so that solder balls or the like are supplied to the ball tray by
10 vibration.

This Sheet Has Been Replaced

